

# TLC69632-Q1 Automotive 100mA, 8-Channel LED Driver with Integrated Oscillator and Advance Diagnostics

## 1 Features

- AEC-Q100 qualified for automotive applications
  - Grade 1: –40°C to 125°C ambient operating temperature
  - Device HBM classification level H1C
  - Device CDM classification level C4B
- **Functional Safety-Compliant**
  - Developed for functional safety applications
  - Documentation available to aid ISO 26262 system design up to ASIL B
- 8 integrated current sinks
  - Programmable 16-bit PWM / Hybrid dimming
  - Programmable 7-bit analog dot correction (DC)
  - Maximum output current / voltage: 100mA / 16V
- Integrated 33MHz oscillator
  - 16-bit PWM output in 500Hz
  - >20KHz refresh rate with enhanced spectrum (ES) PWM
- High speed communication
  - Serial peripheral interface (SPI)
  - Data rates up to 17Mbps
- Power efficiency optimization
  - Adaptive headroom voltage control (AHVC)
  - Device power save mode (PSM)
- EMI mitigation
  - Interface: programmable buffer driving capability
  - Current sinks: phase shifting / spread spectrum
- Protection and Diagnostic
  - LED: open / short detection / health check
  - Current sink: adjacent-pin short / health check
  - Interface: CRC / command error / time-out error / communication watchdog
  - Device: under voltage / ISET out of range / thermal shutdown / memory CRC / OTP CRC / OSC watchdog

## 2 Applications

- Automotive Central information Display
- Automotive Cluster Display
- Automotive Head-up Display

## 3 Description

The TLC69632-Q1 is a LED driver with 8 constant current sink channels which could provide up to 16-bit individual pixel-level LED PWM control. The additional 7-bit dot correction (DC) is also implemented to each channel to control peak current. Each device shares data stream by serial peripheral interface (SPI) which supports up to 511 devices connection. The interface is [software compatible with LED drivers in the same group](#) which can be applied to different application scenarios based on LED current and total LED number.

To optimize overall systematic power efficiency, the device is equipped with adaptive headroom voltage control (AHVC) scheme to optimize headroom voltage across each channel and device. Only the OUT7 pin from the last device of daisy chain is required to be programmed as FB pin to optimize LED supply voltage from DC/DC.

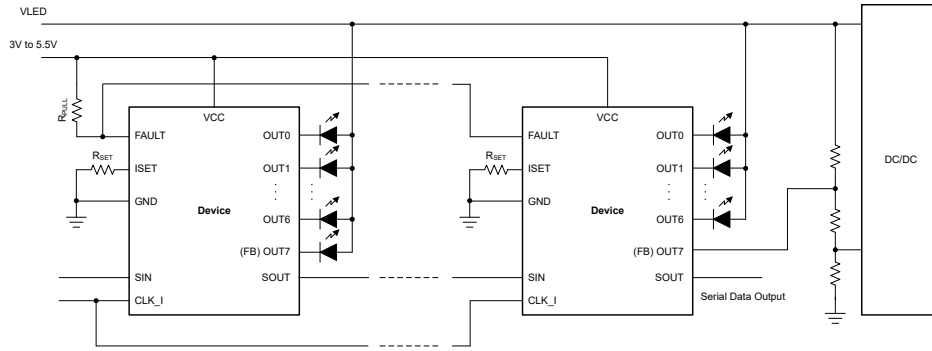
The TLC69632-Q1 is equipped diagnostics for LED, current sink, communication and device.

### Packaging Information

PART NUMBER	PACKAGE <sup>(1)</sup>	BODY SIZE (NOM)
TLC69632-Q1	X2QFN (16) Wettable flank	2.5mm × 2.5mm
	SOT-23-THIN (16)	4.2mm × 2mm

- (1) For all available packages, see the orderable addendum at the end of the data sheet.





**Simplified Schematic**

## Table of Contents

<b>1 Features</b> .....	1	5.3 Trademarks.....	5
<b>2 Applications</b> .....	1	5.4 Electrostatic Discharge Caution.....	5
<b>3 Description</b> .....	1	5.5 Glossary.....	5
<b>4 Device Comparison</b> .....	4	<b>6 Revision History</b> .....	5
<b>5 Device and Documentation Support</b> .....	5	<b>7 Mechanical, Packaging, and Orderable Information</b> ....	6
5.1 Receiving Notification of Documentation Updates.....	5	7.1 Tape and Reel Information.....	8
5.2 Support Resources.....	5		

---

## 4 Device Comparison

PART NUMBER	CHANNEL NUMBER	MAX. CHANNEL CURRENT	FUNCTIONAL SAFETY CLASSIFICATION	INTERFACE	SOFTWARE COMPATIBLE
TLC69621-Q1	8	60mA	Functional Safety-Capable	SPI	Group 1
TLC69624-Q1	24				
TLC69627-Q1	48				
TLC69631-Q1	8	100mA			
TLC69634-Q1	24				
TLC69637-Q1	48				
TLC69622-Q1	8	60mA	Functional Safety-Compliant	SPI	Group 2
TLC69625-Q1	24				
TLC69628-Q1	48				
TLC69632-Q1	8	100mA			
TLC69635-Q1	24				
TLC69638-Q1	48				
TLC69623-Q1	8	60mA	Functional Safety-Compliant	CSI	Group 3
TLC69626-Q1	24				
TLC69629-Q1	48				
TLC69633-Q1	8	100mA			
TLC69636-Q1	24				
TLC69639-Q1	48				

## 5 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

### 5.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](http://ti.com). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 5.2 Support Resources

TI E2E™ [support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 5.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.  
All trademarks are the property of their respective owners.

### 5.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 5.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 6 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

DATE	REVISION	NOTES
March 2026	*	Initial Release

## 7 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGE OPTION ADDENDUM

### PACKAGING INFORMATION

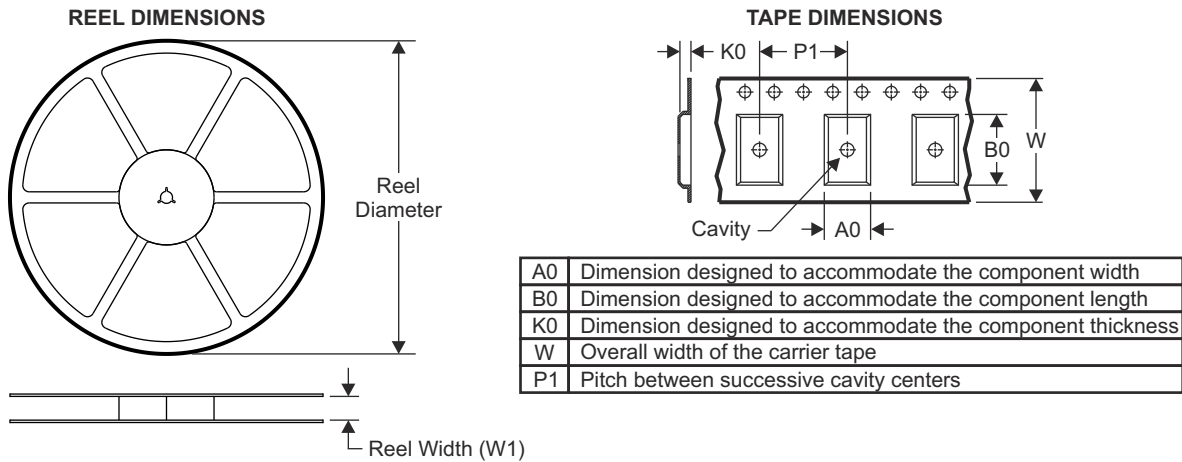
Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/Ball material (4)	MSL rating/Peak reflow (5)	Op temp (°C)	Part marking (6)
TLC69632QDYRQ1	Active	Production	SOT-23-THIN (DYY)   16	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	69622Q1
TLC69632QRUJRQ1	Active	Production	X2QFN (RUJ)   16	5000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	22Q

- (1) **Status:** For more details on status, see our [product life cycle](#).
- (2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.
- (3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.
- (4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part. Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

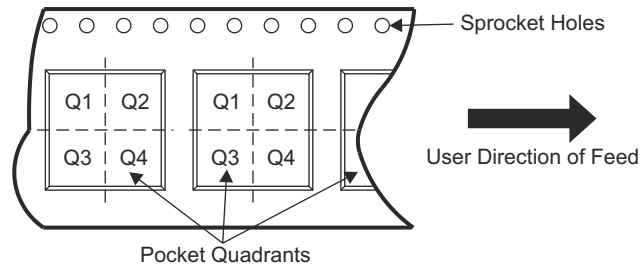
**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## 7.1 Tape and Reel Information

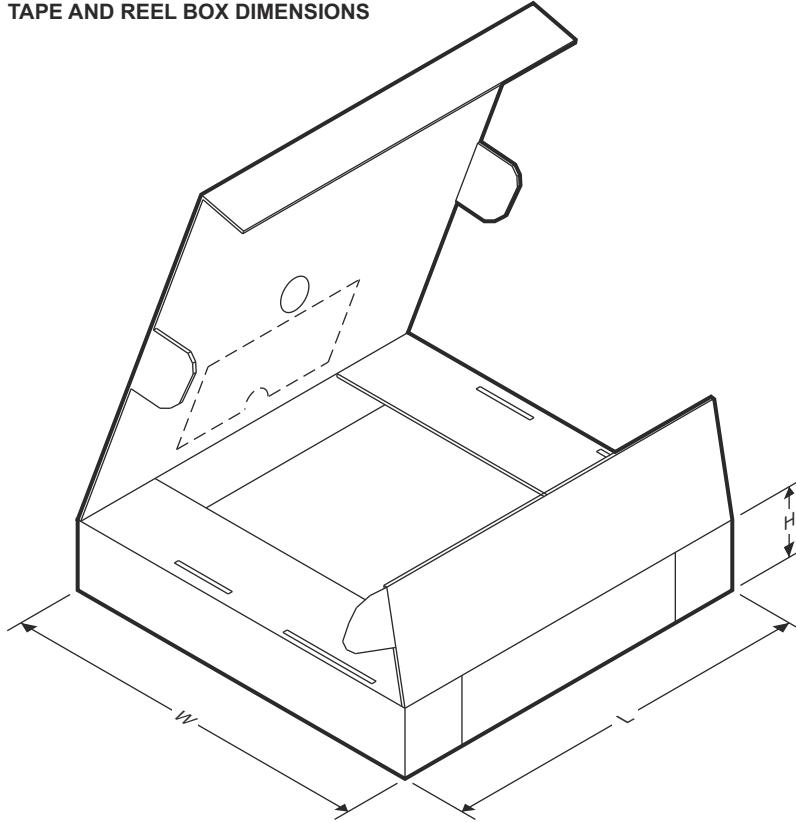


### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



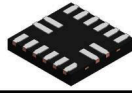
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC69632QDYRQ1	SOT-23-THIN	DYY	16	3000	300	12.4	4.8	3.6	1.6	8	12	Q3
TLC69632QRUJRQ1	X2QFN	RUJ	16	5000	180	8.4	1.8	1.8	0.48	4	8	Q1

**TAPE AND REEL BOX DIMENSIONS**



Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC69632QDYRQ1	SOT-23-THIN	DYY	16	3000	336.6	336.6	31.8
TLC69632QRUJRQ1	X2QFN	RUJ	16	5000	210	185	35

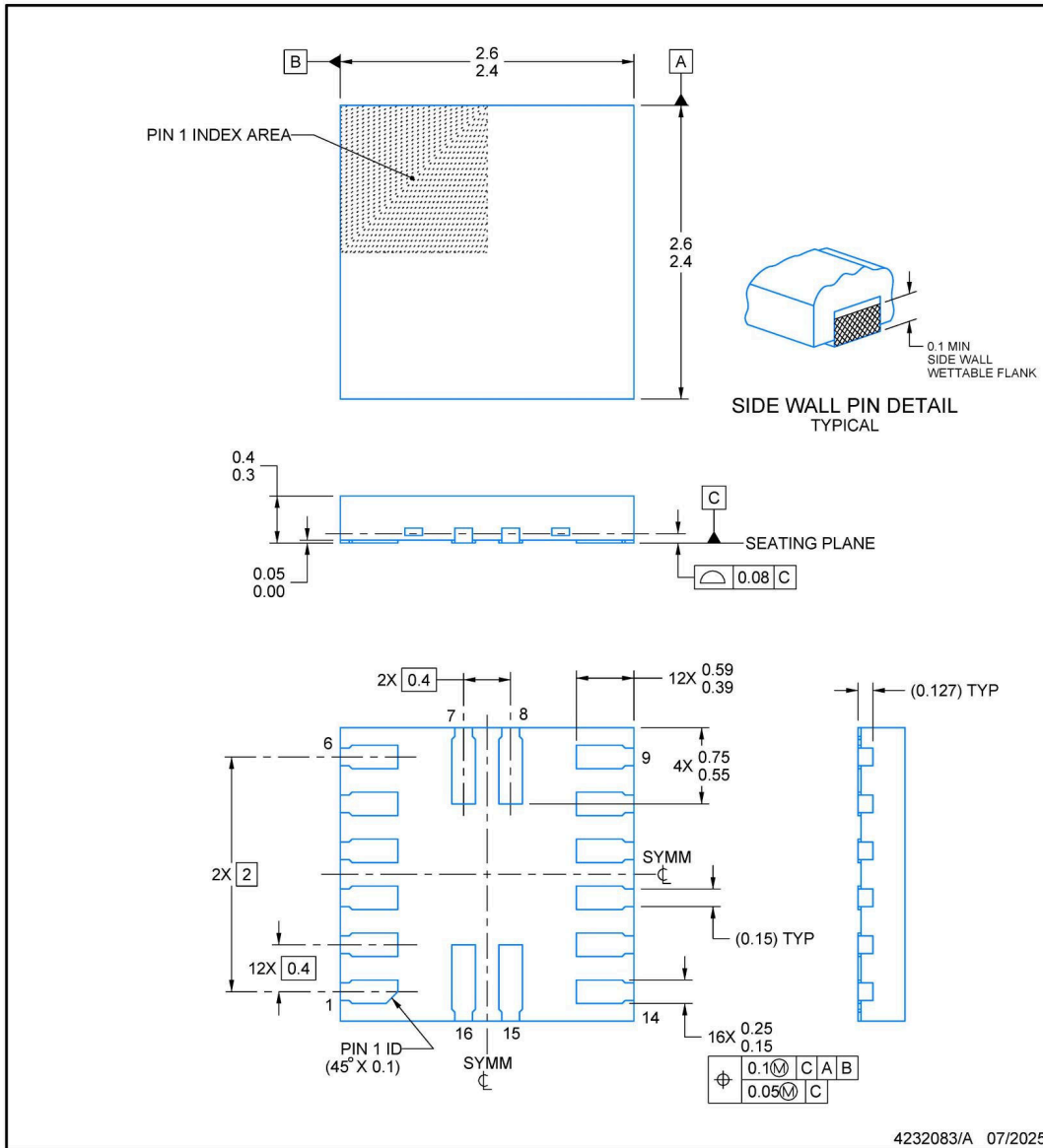
**RUJ0016B**



**PACKAGE OUTLINE**

**X2QFN - 0.4 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



**NOTES:**

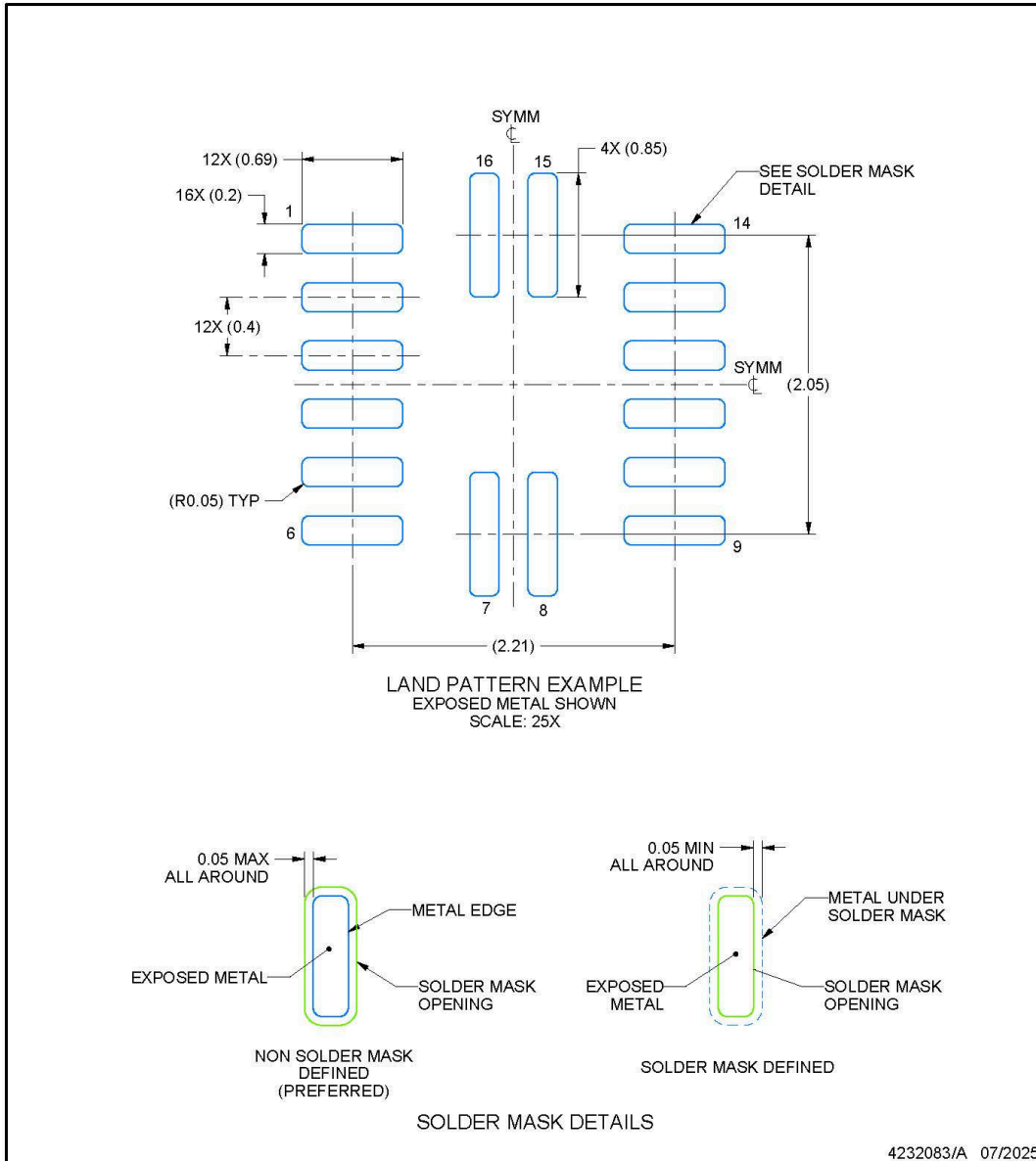
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

**EXAMPLE BOARD LAYOUT**

**RUJ0016B**

**X2QFN - 0.4 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



NOTES: (continued)

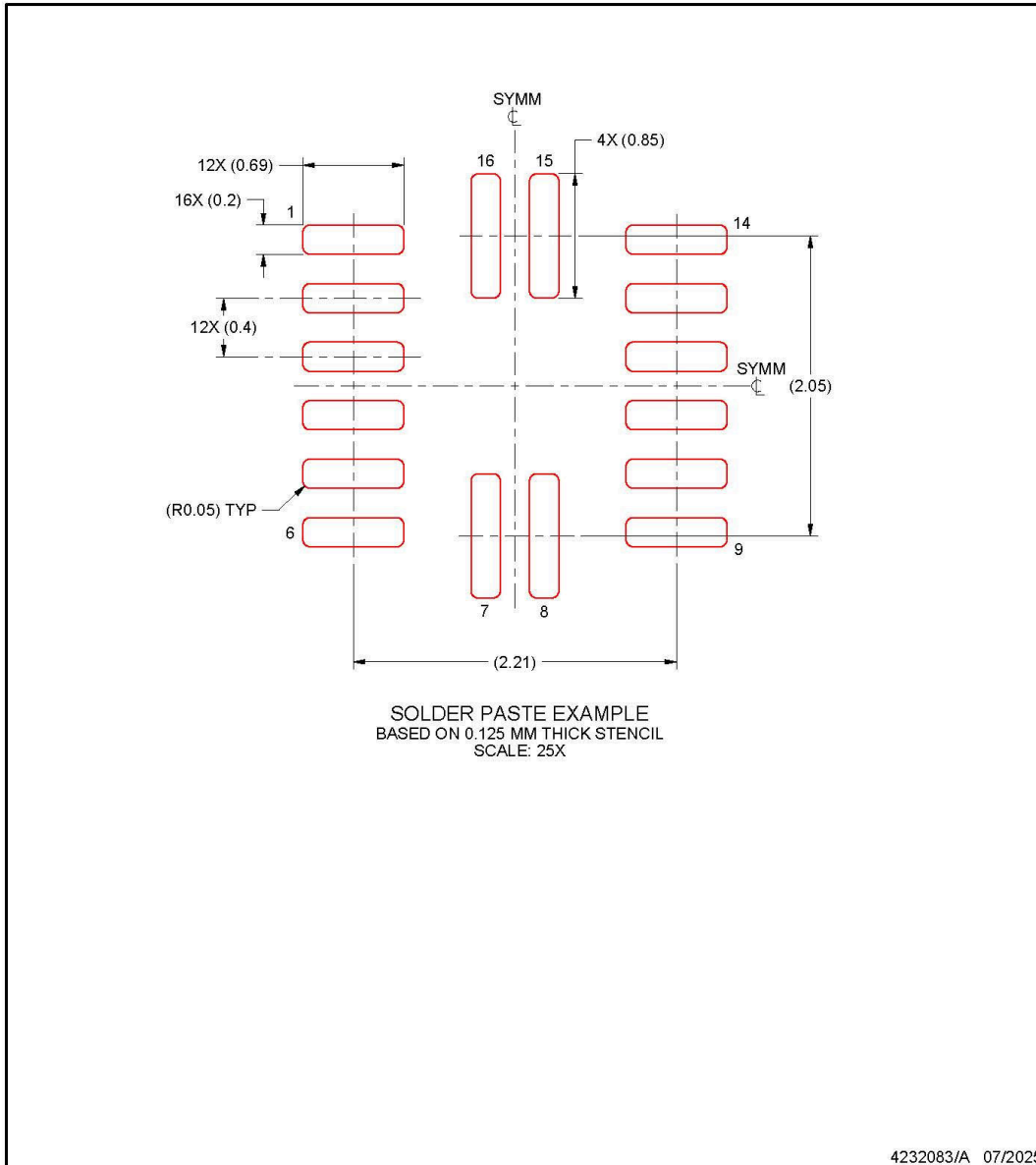
3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).

## EXAMPLE STENCIL DESIGN

**RUJ0016B**

**X2QFN - 0.4 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD

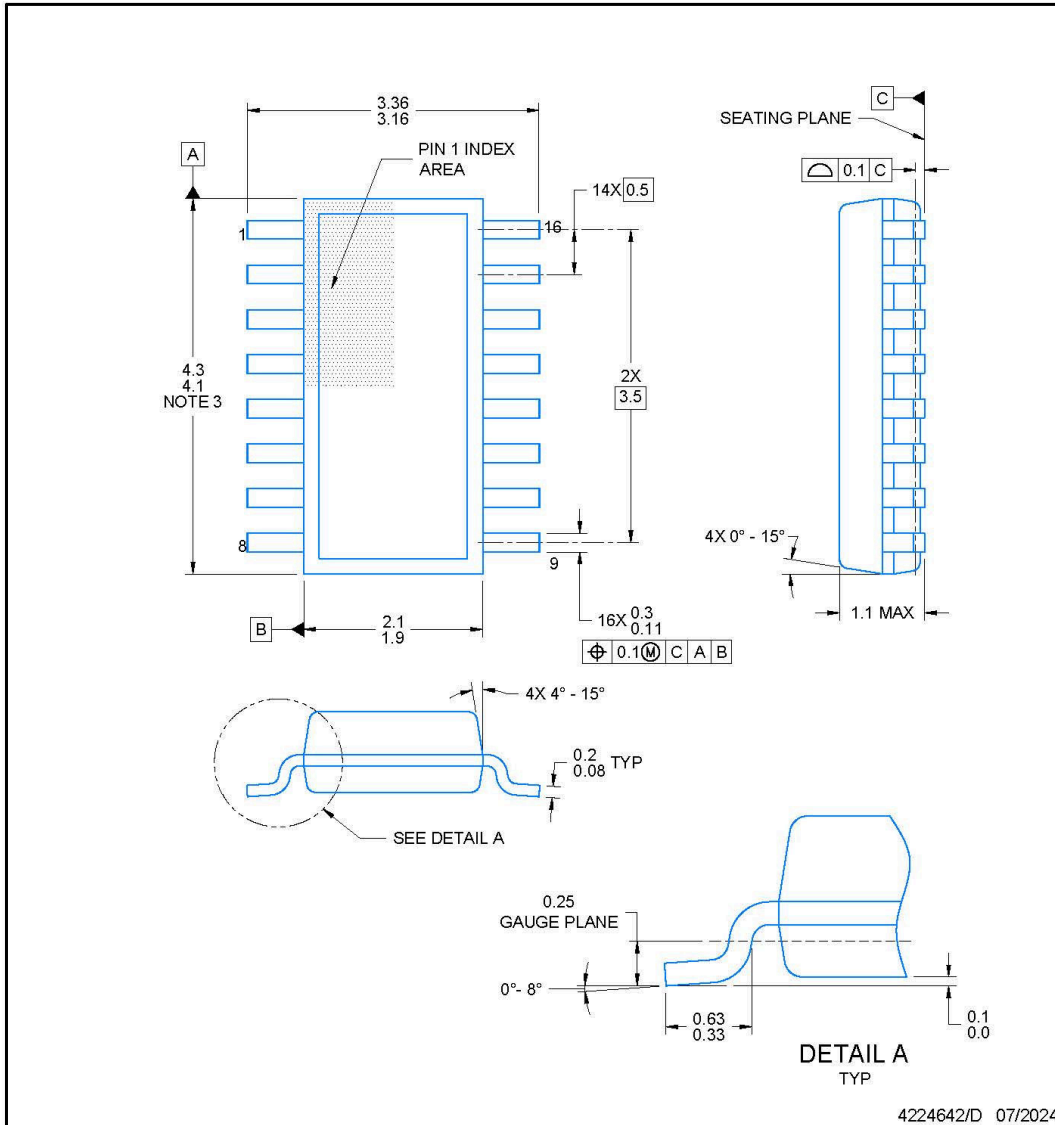


NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

**DYY0016A** **PACKAGE OUTLINE**  
**SOT-23-THIN - 1.1 mm max height**

PLASTIC SMALL OUTLINE

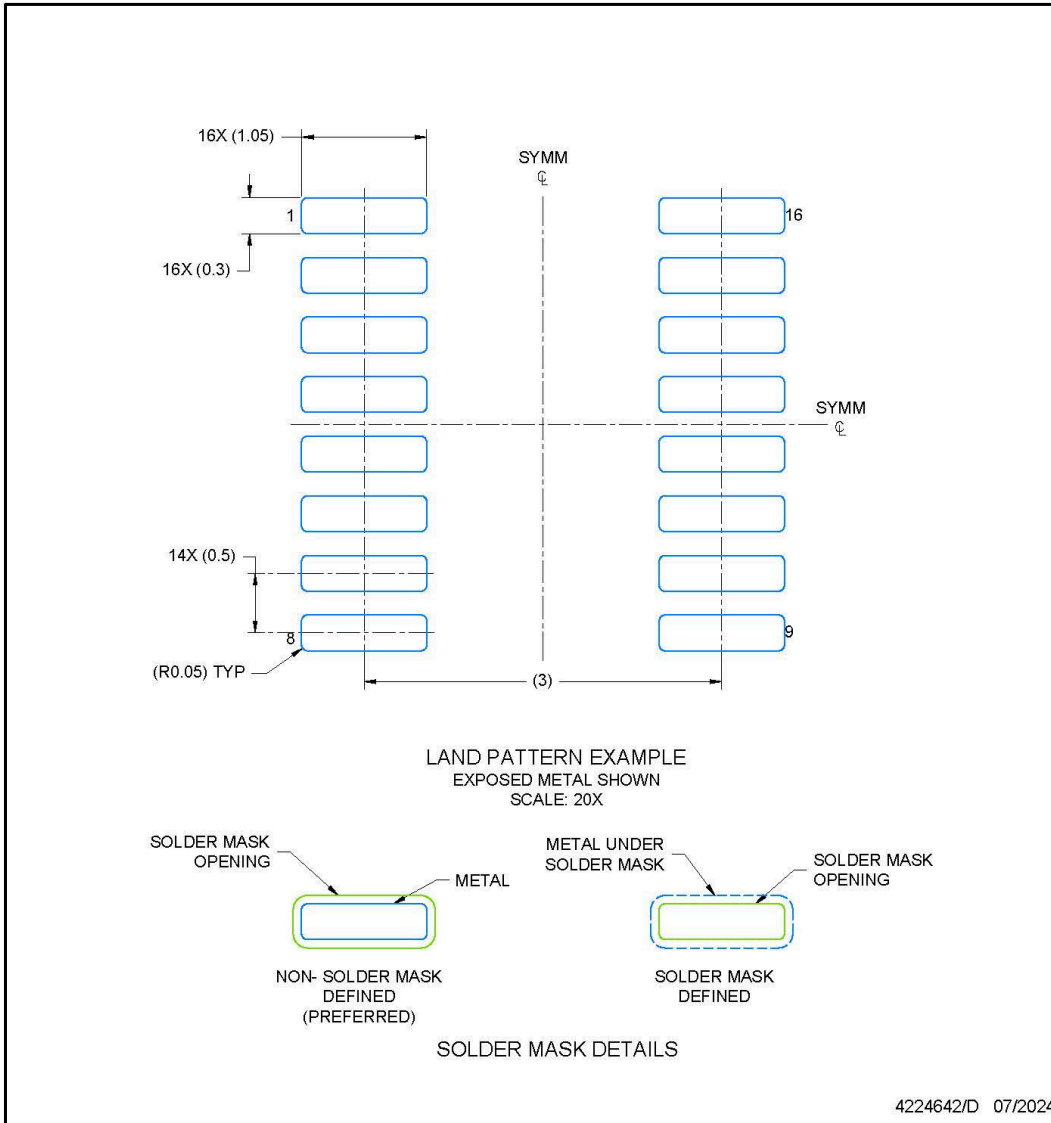


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
5. Reference JEDEC Registration MO-345, Variation AA

**DYY0016A** **EXAMPLE BOARD LAYOUT**  
**SOT-23-THIN - 1.1 mm max height**

PLASTIC SMALL OUTLINE



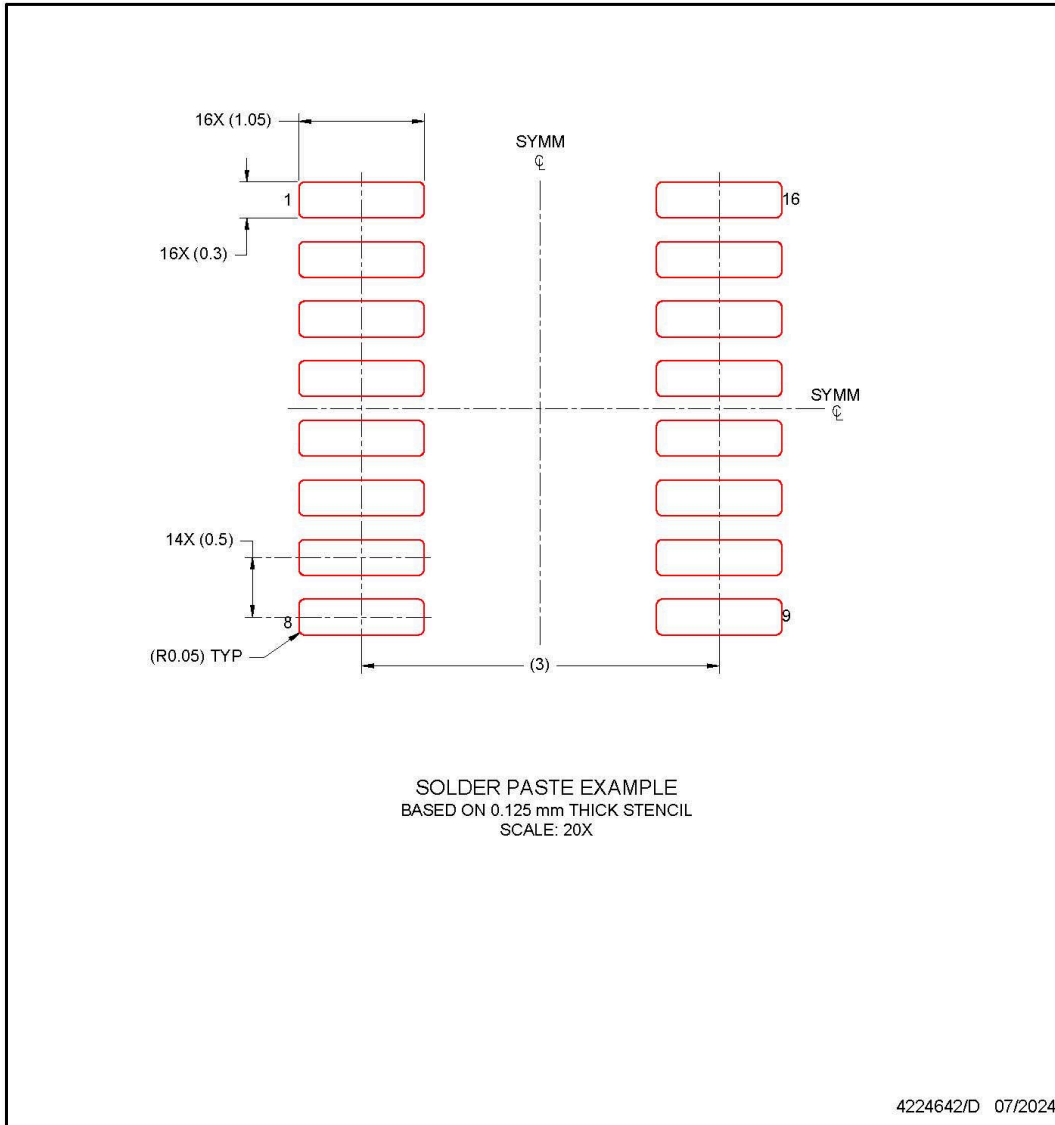
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

**EXAMPLE STENCIL DESIGN**  
**SOT-23-THIN - 1.1 mm max height**

**DYY0016A**

PLASTIC SMALL OUTLINE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">TLC69632QDYRQ1</a>	Active	Production	SOT-23-THIN (DYY)   16	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	69632Q1

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**

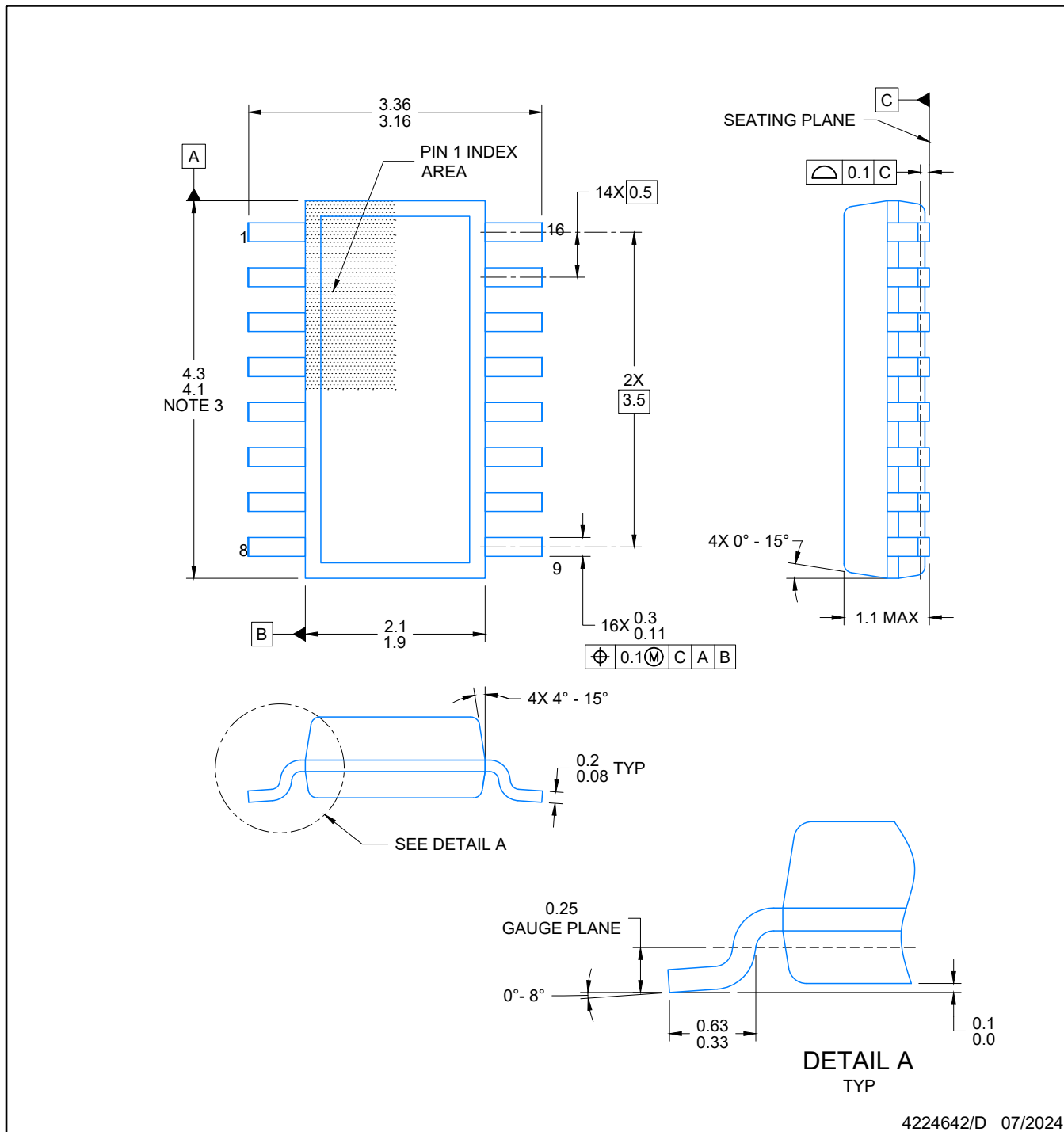

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC69632QDYRQ1	SOT-23-THIN	DYY	16	3000	330.0	12.4	4.8	3.6	1.6	8.0	12.0	Q3

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

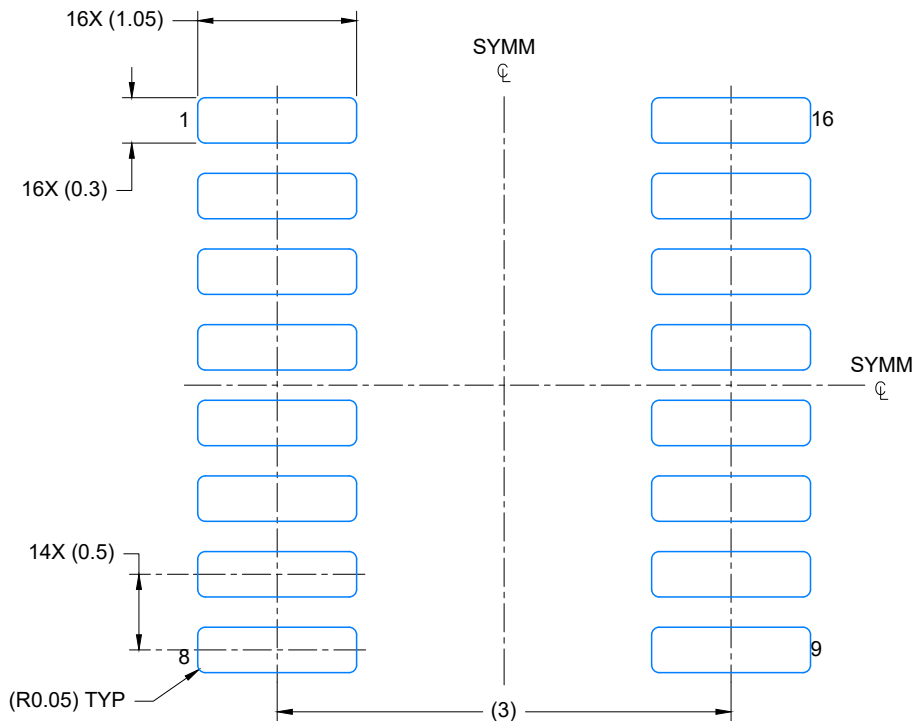
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC69632QDYRQ1	SOT-23-THIN	DYY	16	3000	336.6	336.6	31.8



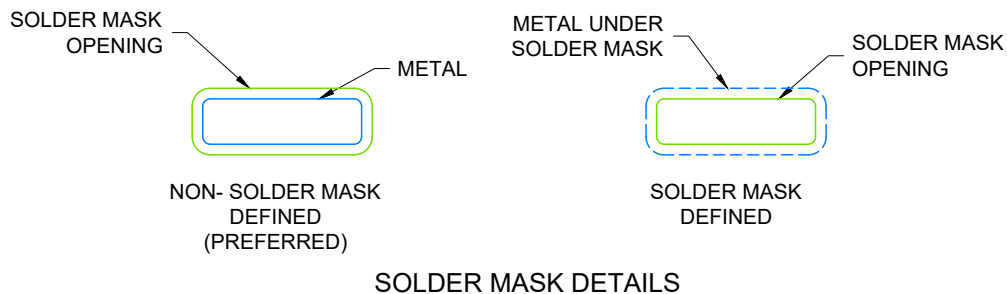
4224642/D 07/2024

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
5. Reference JEDEC Registration MO-345, Variation AA



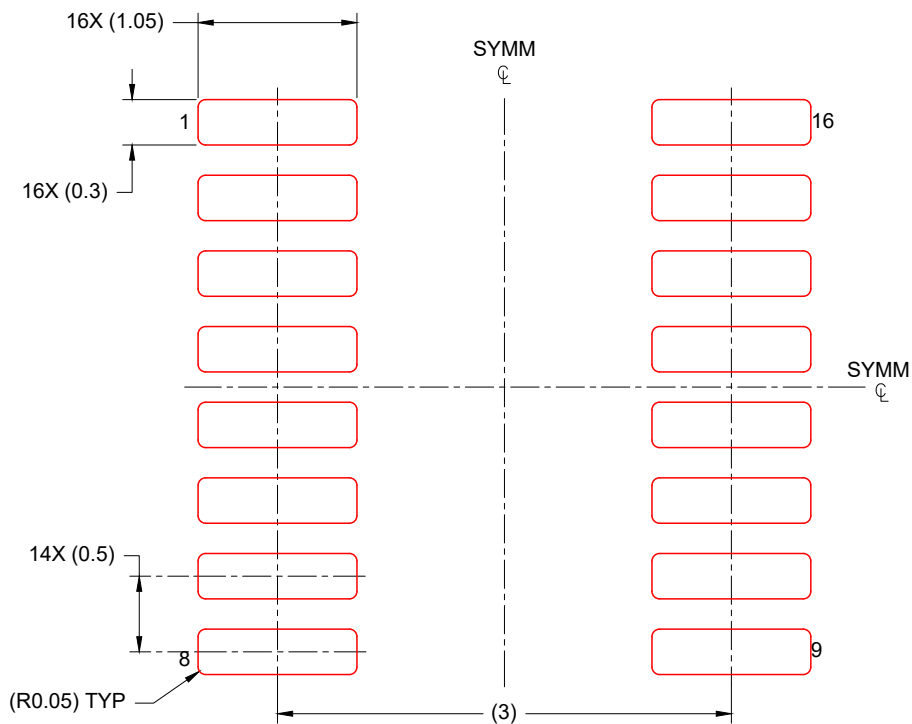
LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 20X



4224642/D 07/2024

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 20X

4224642/D 07/2024

NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.

## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#), [TI's General Quality Guidelines](#), or other applicable terms available either on [ti.com](#) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2026, Texas Instruments Incorporated

Last updated 10/2025